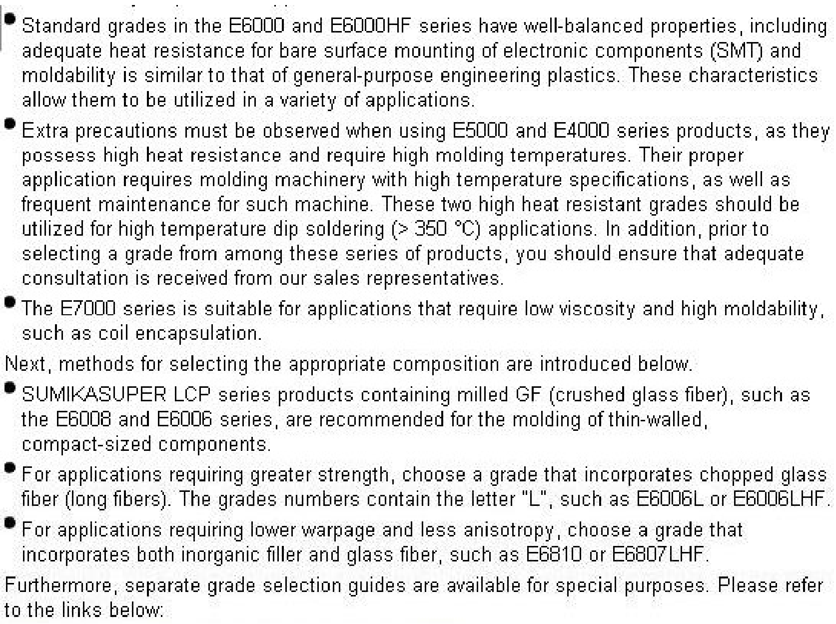

- Standard grades in the E6000 and E6000HF series have well-balanced properties, including adequate heat resistance for bare surface mounting of electronic components (SMT) and moldability is similar to that of general-purpose engineering plastics. These characteristics allow them to be utilized in a variety of applications.
- Extra precautions must be observed when using E5000 and E4000 series products, as they possess high heat resistance and require high molding temperatures. Their proper application requires molding machinery with high temperature specifications, as well as frequent maintenance for such machine. These two high heat resistant grades should be utilized for high temperature dip soldering (> 350 °C) applications. In addition, prior to selecting a grade from among these series of products, you should ensure that adequate consultation is received from our sales representatives.
- The E7000 series is suitable for applications that require low viscosity and high moldability, such as coil encapsulation.

Next, methods for selecting the appropriate composition are introduced below.

- SUMIKASUPER LCP series products containing milled GF (crushed glass fiber), such as the E6008 and E6006 series, are recommended for the molding of thin-walled, compact-sized components.
- For applications requiring greater strength, choose a grade that incorporates chopped glass fiber (long fibers). The grades numbers contain the letter "L", such as E6006L or E6006LHF.
- For applications requiring lower warpage and less anisotropy, choose a grade that incorporates both inorganic filler and glass fiber, such as E6810 or E6807LHF.

Furthermore, separate grade selection guides are available for special purposes. Please refer to the links below:

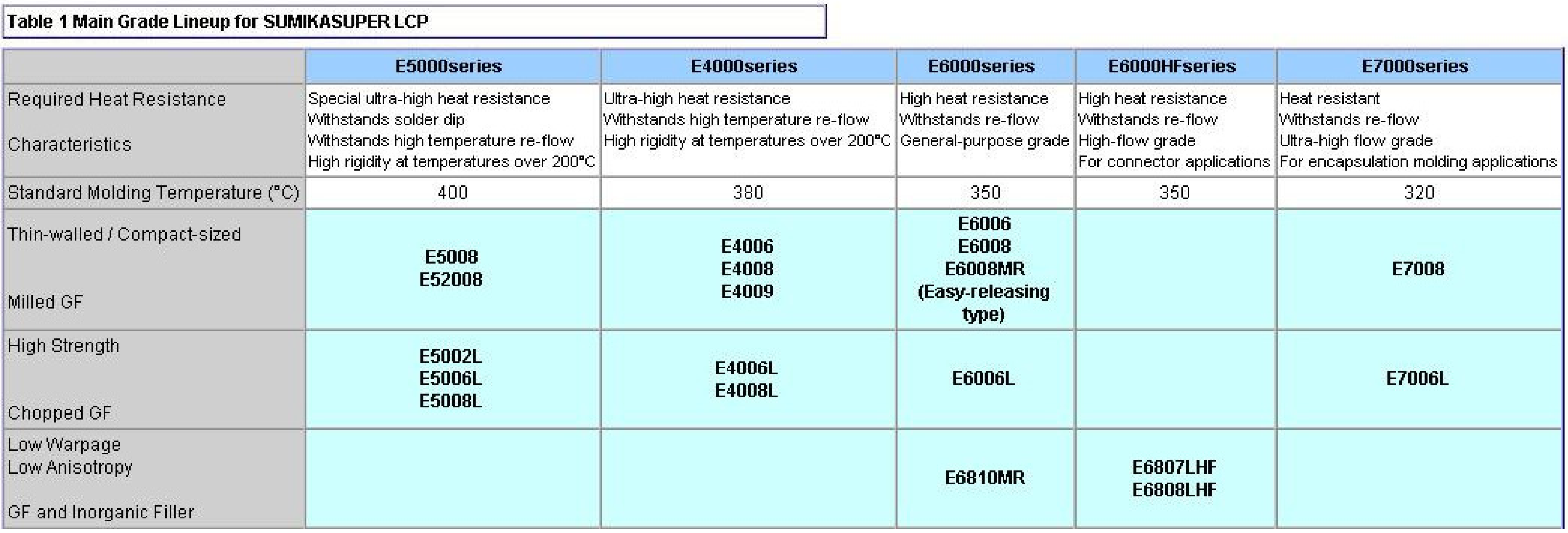

Table 1 Main Grade Lineup for SUMIKASUPER LCP

	E5000series	**E4000series**	**E6000series**	**E6000HFseries**	**E7000series**
Required Heat Resistance Characteristics	Special ultra-high heat resistance Withstands solder dip Withstands high temperature re-flow High rigidity at temperatures over 200°C	Ultra-high heat resistance Withstands high temperature re-flow High rigidity at temperatures over 200°C	High heat resistance Withstands re-flow General-purpose grade	High heat resistance Withstands re-flow High-flow grade For connector applications	Heat resistant Withstands re-flow Ultra-high flow grade For encapsulation molding applications
Standard Molding Temperature (°C)	400	380	350	350	320
Thin-walled / Compact-sized Milled GF	**E5008** **E52008**	**E4006** **E4008** **E4009**	**E6006** **E6008** **E6008MR (Easy-releasing type)**		**E7008**
High Strength Chopped GF	**E5002L** **E5006L** **E5008L**	**E4006L** **E4008L**	**E6006L**		**E7006L**
Low Warpage Low Anisotropy GF and Inorganic Filler			**E6810MR**	**E6807LHF** **E6808LHF**	